

Final Product Change Notification

202003004F01

Issue Date: 10-Apr-2020
Effective Date: 24-Jul-2020
 Dear *Gordon Love*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from Nexperia.
 For detailed information we invite you to [view this notification online](#)



Change Category

- | | | | | |
|---|--|--|---|---|
| <input checked="" type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input checked="" type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input checked="" type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

Assembly site transfer of SOT363 (SC-88) package

Details of this Change

Nexperia assembly site transfer of SOT363 (SC-88) package from ATSN (assembly and test center Seremban Malaysia) to ATGD (assembly and test center Guangdong China).

The assembly site transfer is combined with the introduction of a new epoxy mould compound (CEL-1700HF). Additionally for one product type, 8 inch wafer diameter will be released and the bond wire material will be changed from gold (Au) to copper (Cu).

Following the details:

Current products

- assembly site ATSN
- epoxy mould compound: GR646 (Henkel), 3400FPG (Panasonic) or EME-E500HK (Sumitomo).
- 6 inch (where affected)
- Au wire (where affected)

Changed products:

- assembly site ATGD
- epoxy mould compound: CEL-1700HF (Hitachi)

- 6 or 8 inch (where affected)
- Cu wire (where affected)

Production on 8 inch wafer diameter implies the use of the respective 8 inch wafer process technology.

Why do we Implement this Change

- to achieve a higher and flexible supply capability.
- improved epoxy mould compound adhesive
- to increase flexibility and volume ramp-up.
- aligning with world technology standards, Nexperia continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.

Identification of Affected Products

Changed products will be identified by the assembly identifier on the marking and label and the date code after implementation.

Product Availability

Sample Information

Samples are available upon request

Latest sample request date for PCN samples is 10-May-2020.

Production

Planned first shipment 24-Jul-2020

Impact

No impact to the products' functionality anticipated.

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file 

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 10-May-2020. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact Nexperia "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

e-mail address PCN-Bipolar.Discretes@nexperia.com

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 90 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

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